

Appl. No. 10/511,460

IN THE CLAIMS

1. (Currently Amended) A module for a data carrier, which module (3) includes an integrated component (4) with at least two connection contacts and, for each connection contact, a connecting part which is electrically conductively connected to the relevant connection contact, the connection contacts being constructed so as to project from the integrated component **and provide a first major surface;** and the connecting parts consisting of metal and being constructed so as to be plate-shaped, the connecting parts comprising remnants of raised portions which have been formed by mechanical deformation of the connecting parts, which remnants project from the connecting parts in the direction of the connection contacts;

wherein two or more of the remnants which project from each of the connecting parts in the direction of the connection contacts are physically in contact with the first major surface of the relevant connection contact

2. (Previously Presented) A module as claimed in claim 1, in which the remnants of raised portions originate from raised portions formed by stamping.

3. (Previously Presented) A module as claimed in claim 1, in which the remnants of raised portions have a height of between 1.0 μm and 10 μm .

4. (Currently Amended) A module as claimed in claim 1, in which the remnants of raised portions have a lateral length of between 10 μm and 50 μm in the a transitional zone to the connecting parts.

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5. (Previously Presented) A module as claimed in claim 1, in which a filler material which encloses the connection contacts and the remnants of raised portions is provided between the integrated component and the connecting parts.
6. (Previously Presented) A module as claimed in claim 5, in which the filler material is formed by a foil which consists of a synthetic material and can be softened at least once by heating.
7. (Currently Amended) A data carrier provided with a module which includes an integrated component with at least two connection contacts and, for each connection contact, a connecting part which is electrically conductively connected to the relevant connection contact, the connection contacts being constructed so as to project from the integrated component **and provide a first major surface;** and the connecting parts consisting of metal and being constructed so as to be plate-shaped, the connecting parts comprising remnants of raised portions which have been formed by mechanical deformation of the connecting parts, which remnants project from the connecting parts in the direction of the connection contacts;
- wherein two or more of the remnants which project from each of the connecting parts in the direction of the connection contacts are physically in contact with the first major surface of the relevant connection contact.**

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8. (Previously Presented) A data carrier as claimed in claim 7, in which the remnants of raised portions originate from raised portions formed by stamping.

9. (Previously Presented) A data carrier as claimed in claim 7, in which the remnants of raised portions have a height of between 1.0 μm and 10 μm .

10. (Currently Amended) A data carrier as claimed in claim 7, in which the remnants of raised portions have a lateral length of between 10 μm and 50 μm in the a transitional zone to the connecting parts.

11. (Previously Presented) A data carrier as claimed in claim 7, in which a filler material which encloses the connection contacts and the remnants of raised portions is provided between the integrated component and the connecting parts.

12. (Previously Presented) A data carrier as claimed in claim 11, in which the filler material is formed by a foil which consists of a synthetic material and can be softened at least once by heating.